



Title of Change:	Change of assembly process flow for LA4425PV SSOP44
Proposed first ship date:	29 March 2017
Contact information:	Contact your local ON Semiconductor Sales Office or < Takeshi2.Hoshino @onsemi.com>, <Makoto.Tsubonoya@onsemi.com>, <Naoki.Koyama@onsemi.com>, <Yoshitaka.Matsumoto@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	This is typically by a date code (e.g. "Affected products will be identified with date code."), marking, new part number, etc.
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input checked="" type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Tarlac City, Philippines <input type="checkbox"/> External Foundry/Subcon site(s)
Description and Purpose:	<p>Assembly process flow is changed to restrain the burr occurrence on tie-bar cutting process, and achieve the zero defect of the adhered burr by the water blast in EDM process after tie-bar cutting process. (Quality improvement)</p> <p><u><Before Change></u> Molding / Baking → EDM (Resin deflashing) → Laser marking → Plating → DTF (Tie bar cutting, Trimming and Forming)</p> <p><u><After Change></u> Molding / Baking → DD (Tie bar cutting) → EDM (Resin deflashing) → Plating → Laser marking → TF (Trimming and Forming)</p>
Electrical Characteristic Summary:	Electrical characteristics are not impacted.
List of Affected Standard Parts:	LA4425PV-TLM-H LA4425PV-MPB-H